

描述 / Descriptions

表面贴装整流二极管，反向电压：50V~1000V，正向电流：2.0A，SMA 封装。
Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage : 50 to1000V,Forward Current:2.0A ,SMA package.

特征 / Features

玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

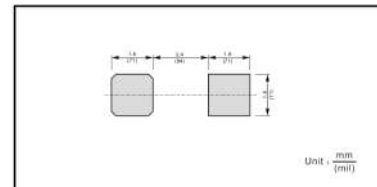


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S2A	S2B	S2D	S2G	S2J	S2K	S2M	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	I _{F(AV)}	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	50							A
Typical Junction Capacitance at V _R =4V f=1MHz	C _j	25							pF
Typical Thermal Resistance ¹⁾	R _{θJA}	65							°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55~+150							°C

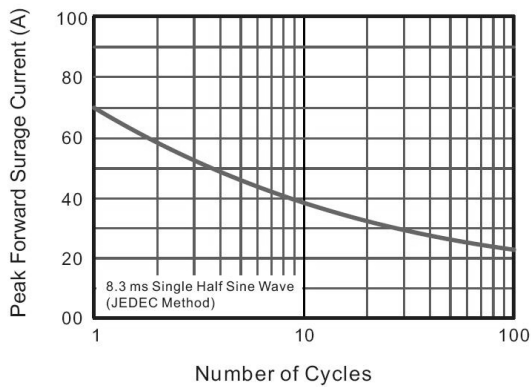
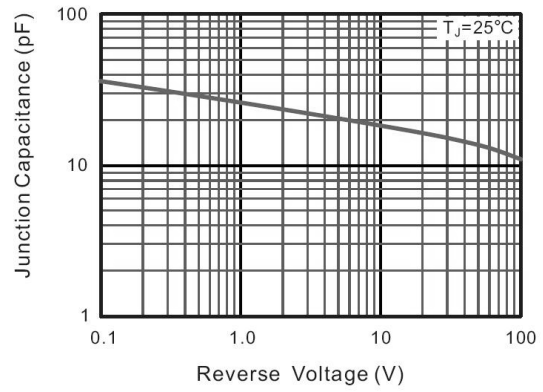
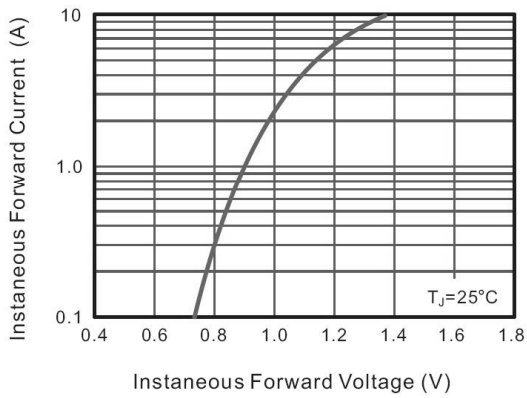
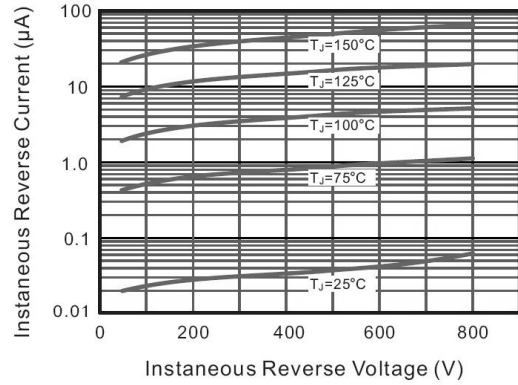
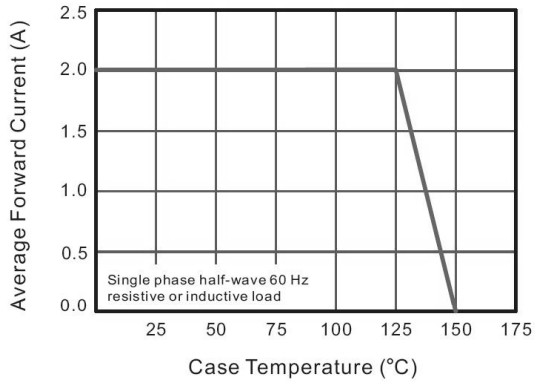
Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X5cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

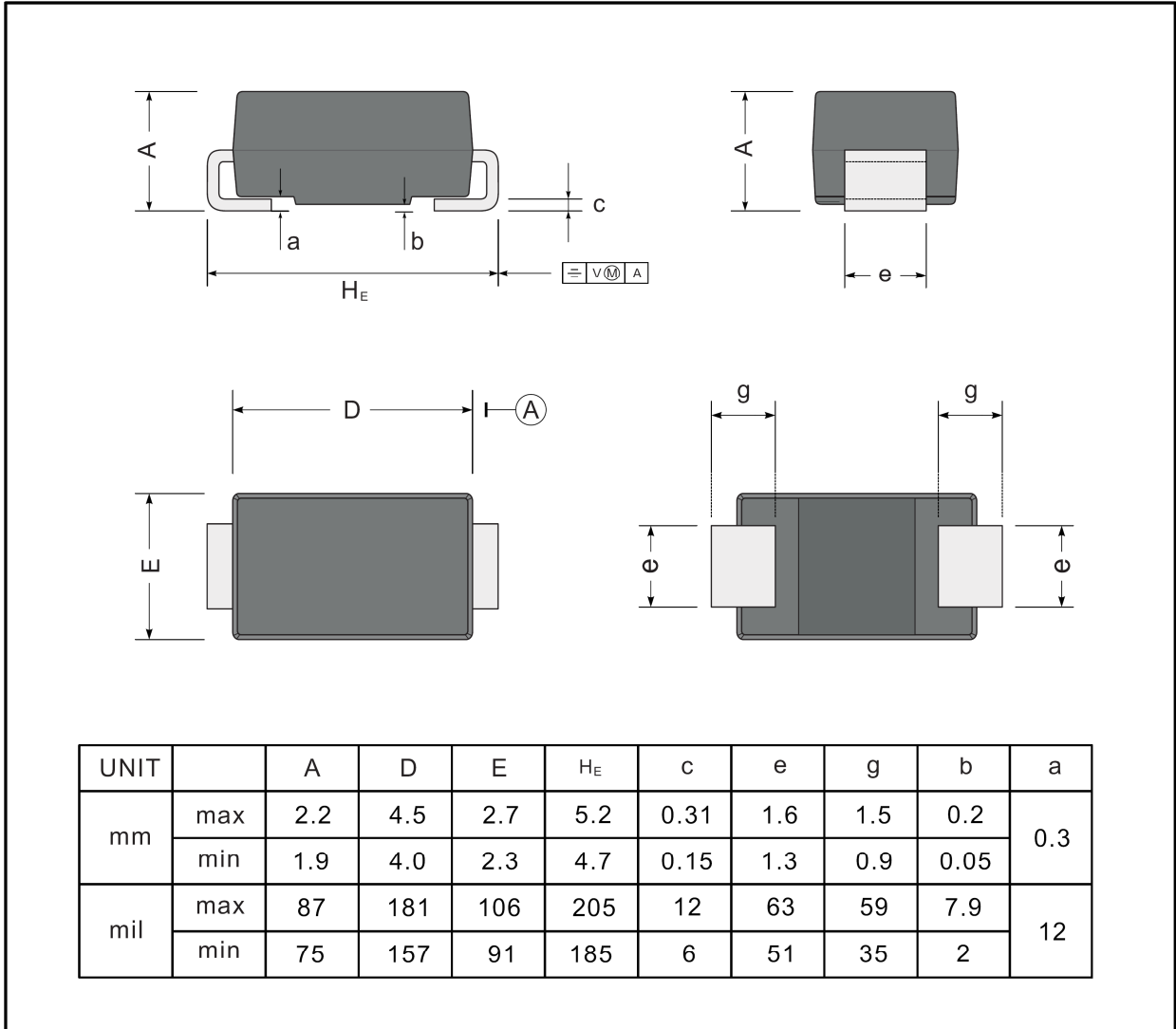
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			S2A	S2B	S2D	S2G	S2J	S2K	S2M	
Maximum Instantaneous Forward Voltage	V _F	I _F =2.0A	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I _R	T _a =25°C	5.0							μA
		T _a =125°C	100							μA

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

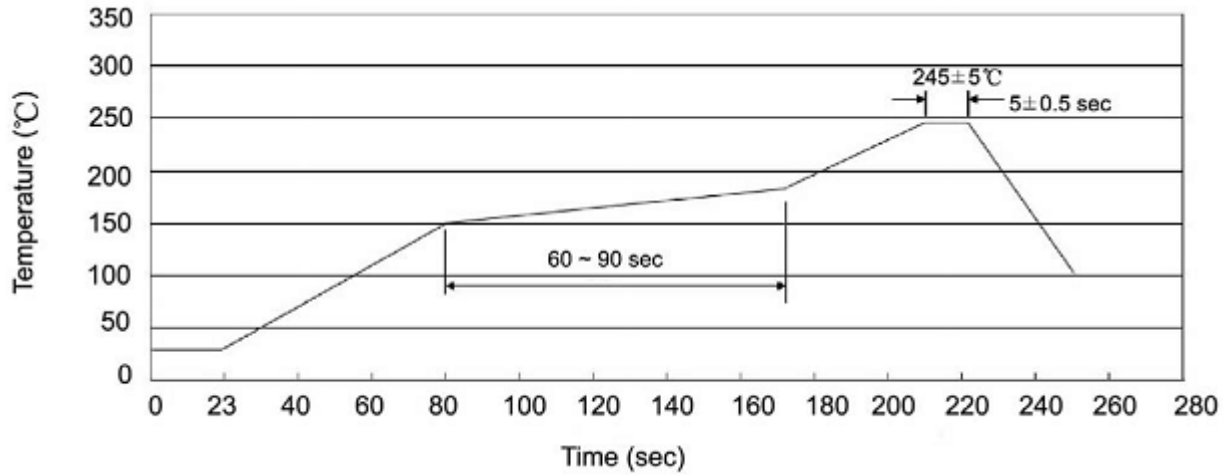
SMA



印章说明 / Marking Instructions

Type number	Marking code
S2A	S2A
S2B	S2B
S2D	S2D
S2G	S2G
S2J	S2J
S2K	S2K
S2M	S2M

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMA	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

使用说明 / Notices